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(12) **United States Design Patent**
Podubni

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- (54) **MODULAR CIRCUIT BOARD**
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- (51) **LOC (11) Cl.** **13-03**
- (52) **U.S. Cl.**
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- (58) **Field of Classification Search**
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361/761, 807; 439/55, 65, 68, 76.1, 92,
439/93, 95
CPC H05K 3/00; H05K 3/30; H05K 3/301;
H05K 3/303; H05K 3/34; H05K 3/3405;
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H05K 1/00
See application file for complete search history.

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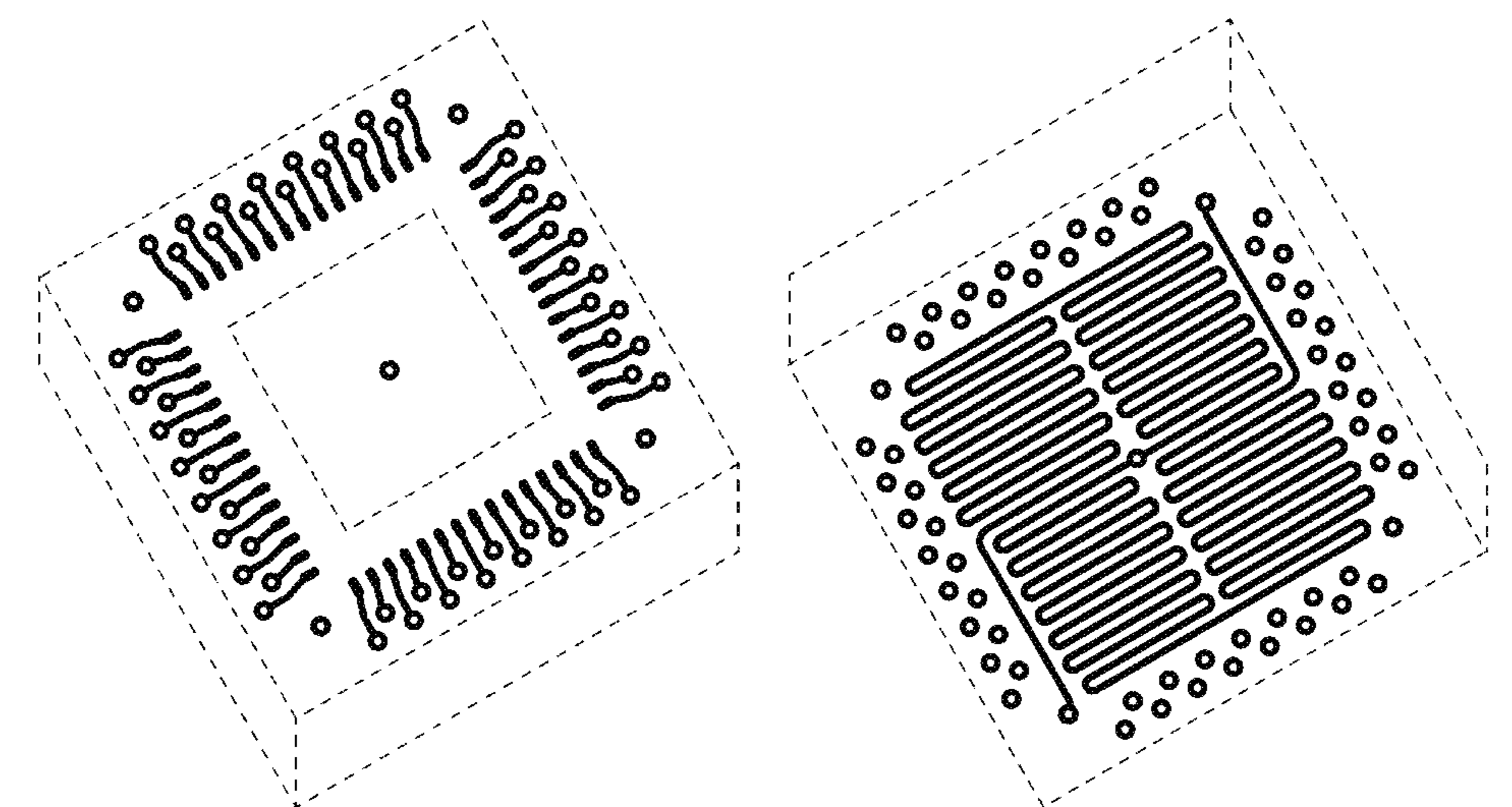
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(57) **CLAIM**
The ornamental design for a modular circuit board, as shown and described.

DESCRIPTION
FIG. 1 is a top perspective view of a modular circuit board, showing my new design;
FIG. 2 is a bottom perspective view thereof;
FIG. 3 is a top view thereof;
FIG. 4 is a bottom view thereof; and,
FIG. 5 is a side view thereof, all other side views being a mirror image thereof.
The broken lines shown in the drawings represent portions of the modular circuit board that form no part of the claimed design.

1 Claim, 5 Drawing Sheets



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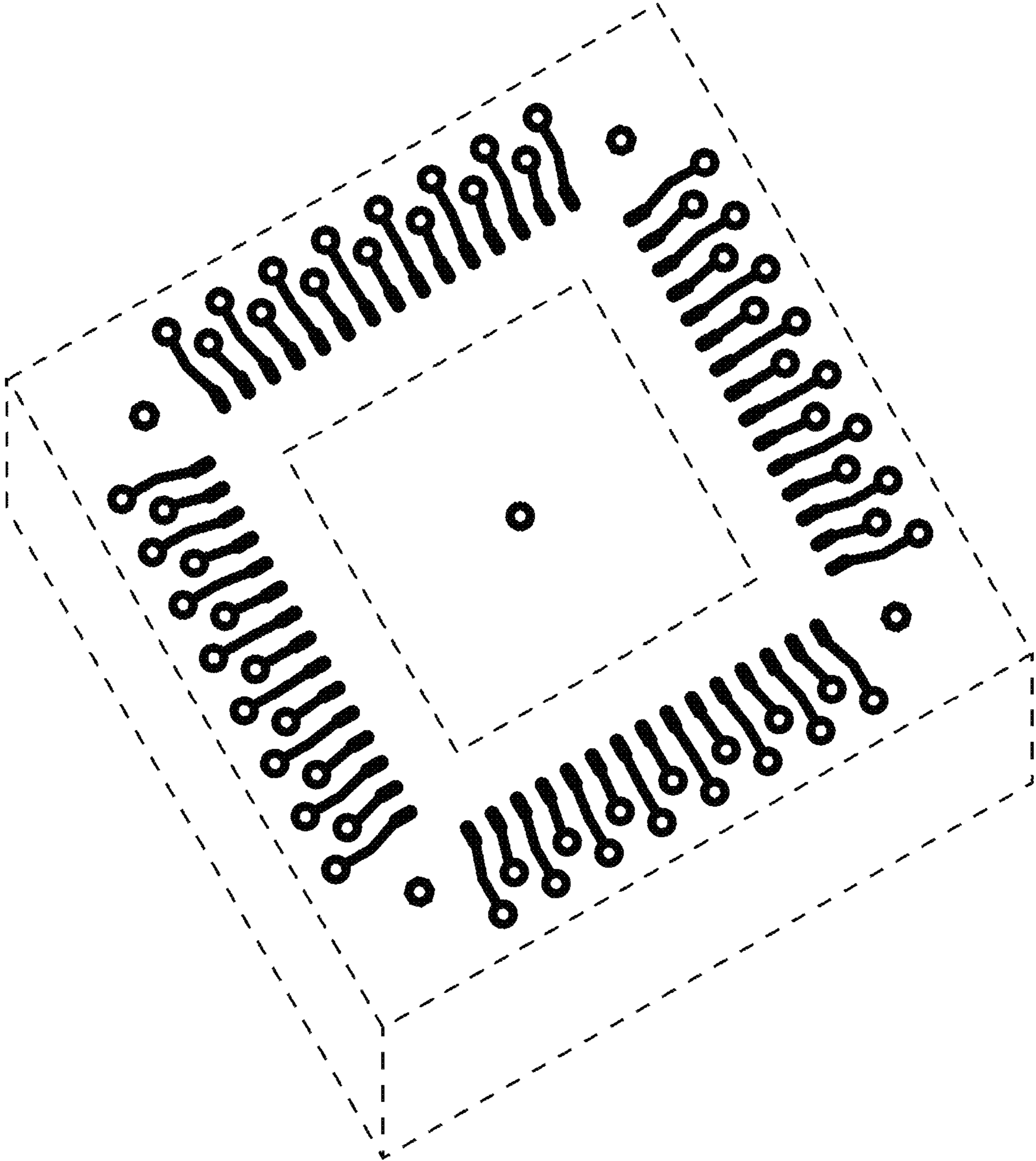


FIG. 1

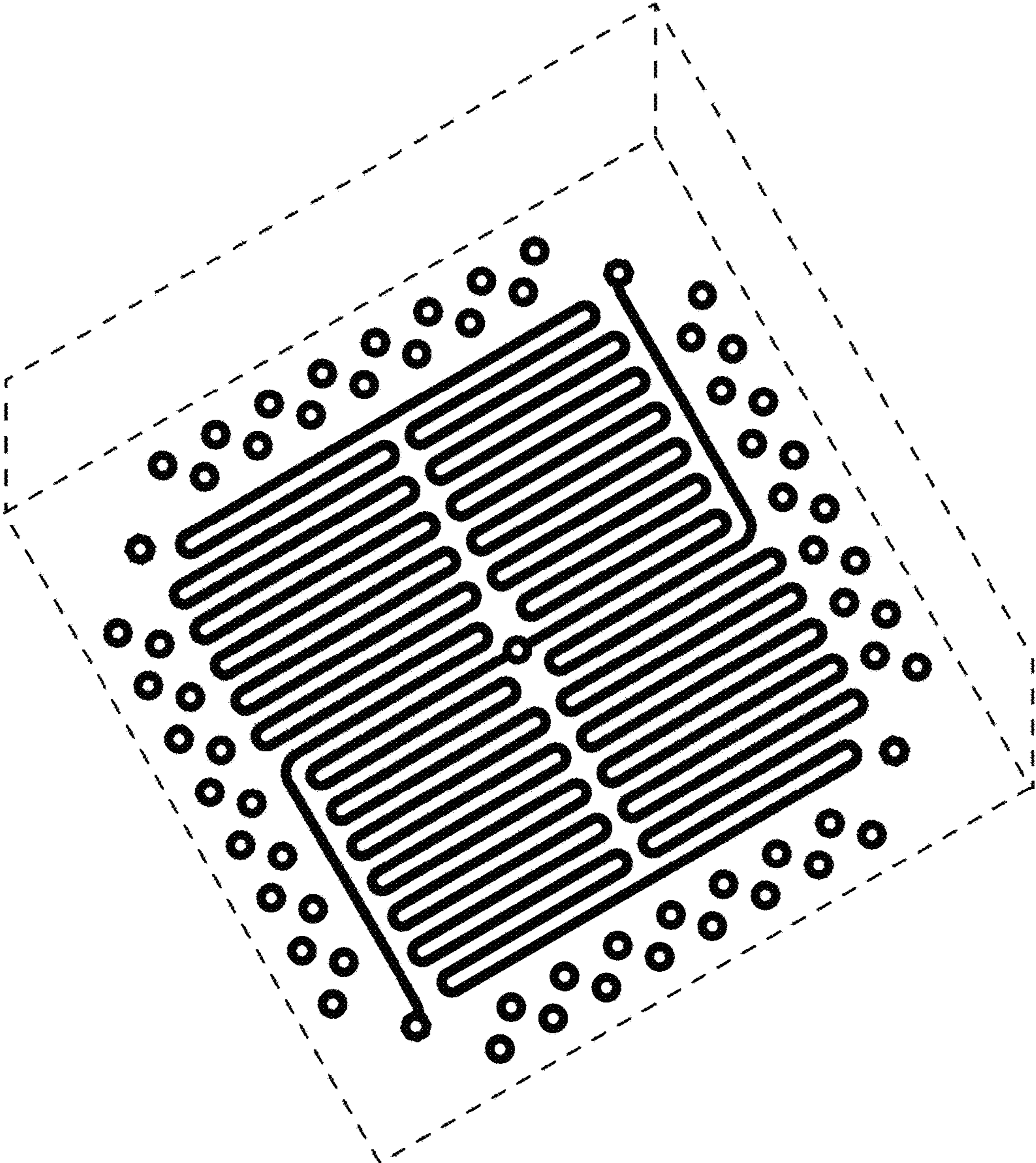


FIG. 2

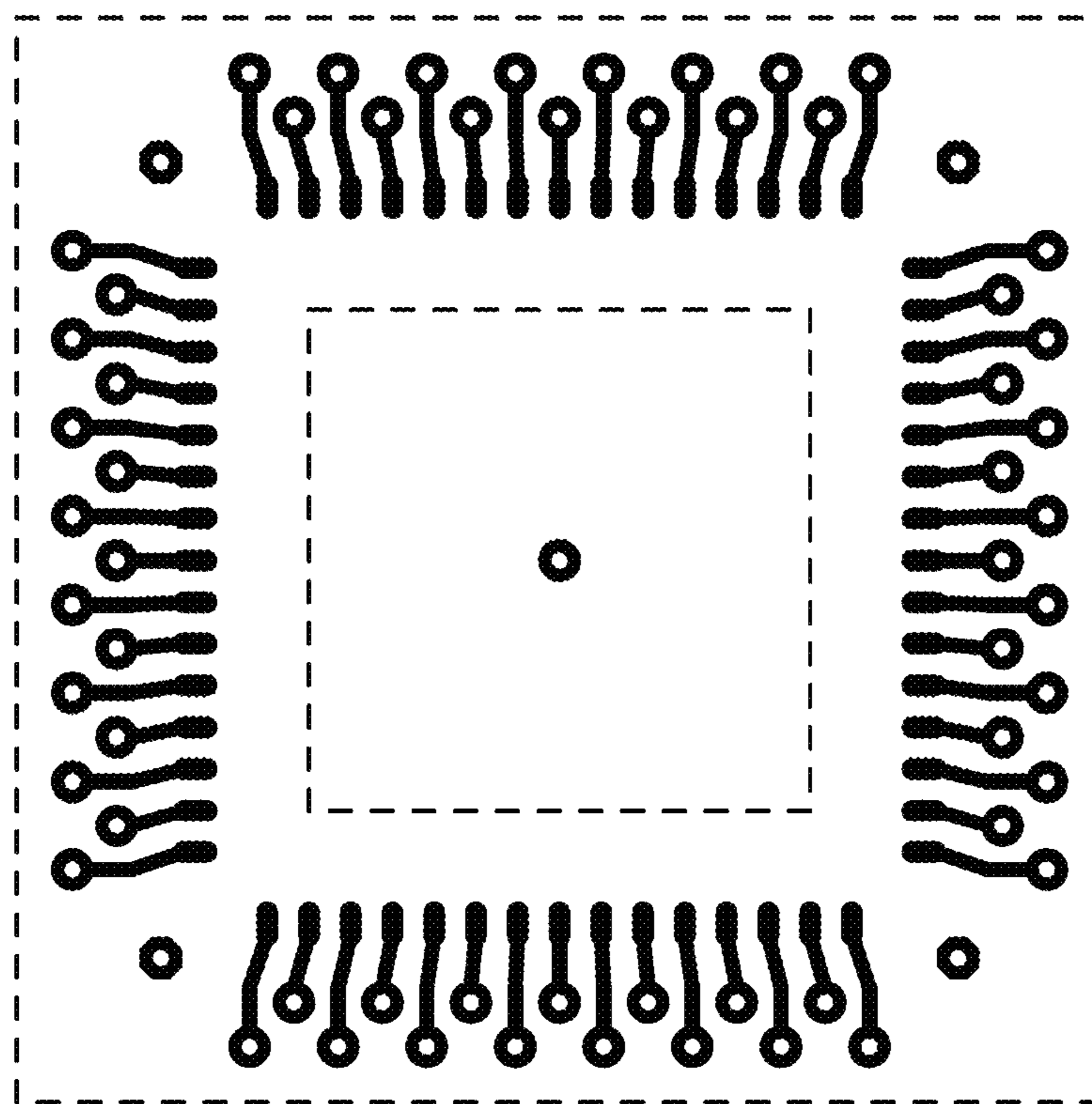


FIG. 3

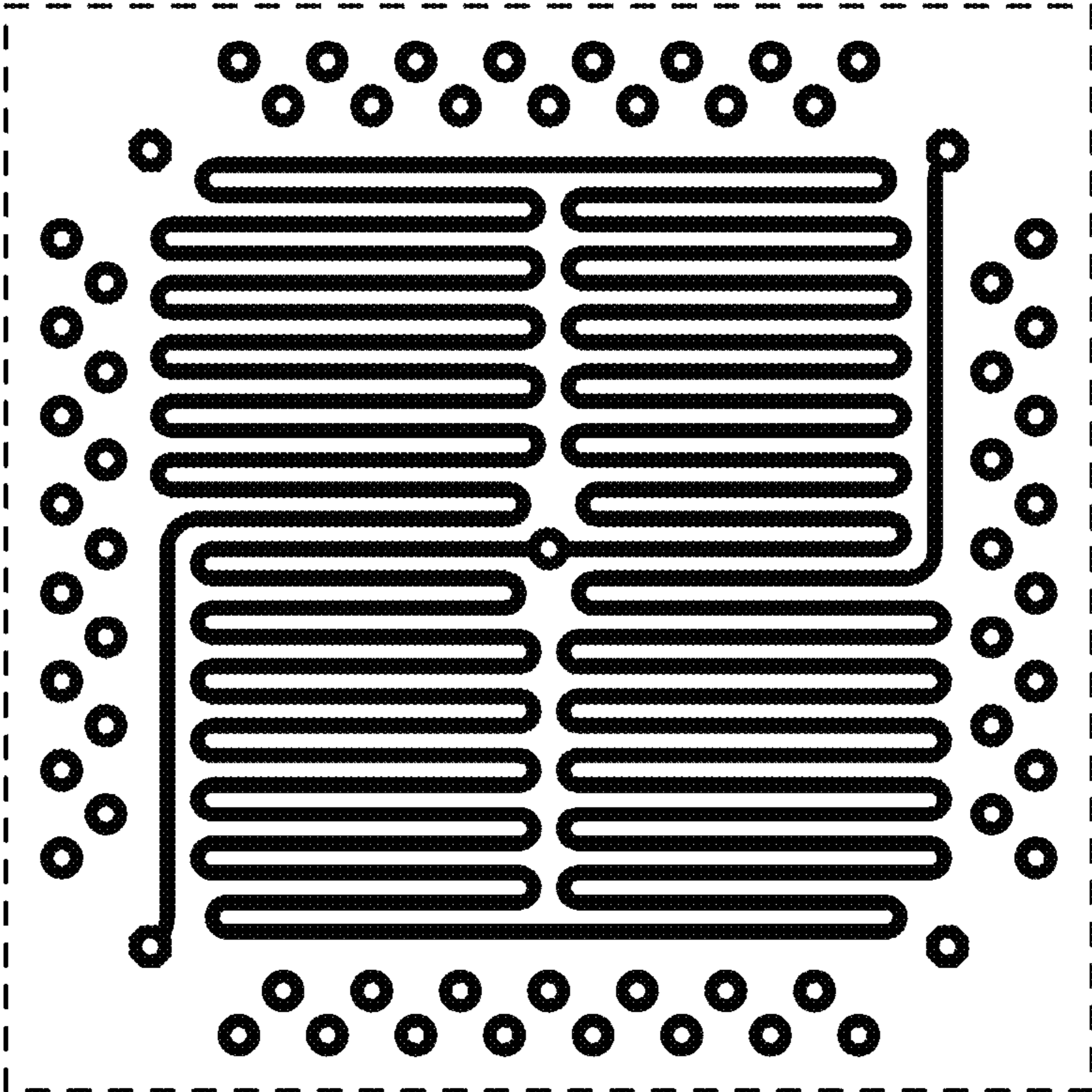


FIG. 4



FIG. 5